

ATTACHMENT A

In the following, insertions are underlined and deletions are enclosed in brackets.

The paragraph starting on page 5, line 9 is amended as follows:

"A locking pad is coined into an outer end portion of each lead adjacent to the frame, a wire bonding pad is coined into an inner end portion of each lead adjacent to the die pad, and a recessed shoulder is coined into the lower surface of the die pad around a central portion thereof. The wire bonding pads increase the area of the leads adjacent to the die pad to enable reliable wire bonds to be made to the leads. The locking pads, wire bonding pads, and recessed shoulder provide locking steps in the leadframe and increase the area of adhesion between the leadframe and an over-molded plastic body to lock the two together more securely and increase their resistance to delamination and the subsequent penetration of the package by moisture. A mounting and interconnection land is defined on the lower surface of each lead between the locking pad on its outer end and the wire bonding pad on its inner end."

The paragraph starting on page 12, line 4 is amended as follows:

"Those skilled in the packaging art will understand that many variations of the particular embodiments of the novel leadframe and package illustrated and described herein are possible, depending on the particular problem at hand. For example, al-though a square package 68 is illustrated in the figures, a rectangular or polygonal package is

thereof. Further, the leads 16 can be extended outside of the body 66 of the pack-age 68

and the lands 48 over-molded with plastic to yield a package with peripheral leads, such as those found in a conventional "quad-flat" package."

ATTACHMENT B

This response amends claim 13 as follows:

- 1 13. (Amended) A semiconductor package, comprising:
- 2 a metal leadframe, including a plurality of elongate leads arrayed around a central
- 3 region thereof, each lead having an outer end extending away from the central region and
- 4 an inner end extending toward the central region;
- 5 a spatulate locking pad in an outer portion of each lead adjacent to its outer end;
- 6 a spatulate wire bonding pad in an inner portion of each lead adjacent to its inner
- 7 end;
- 8 a land defined on a lower surface of each lead between the locking pad and the
- 9 bonding pad; and,
- 10 a die pad attached to the leadframe in the central region thereof and adjacent to
- 11 the inner ends of the leads, the die pad having an upper surface and a lower surface, the
- 12 lower surface having a central portion and a recessed shoulder extending around the cen-
- 13 tral portion.